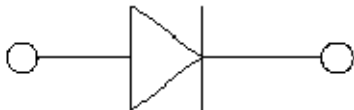


High Speed Switching Diode



Features

- V_R 75V
- I_{FAV} 200mA

Typical Applications

- Extreme fast switches

Mechanical Data

- **Package:** SOD-323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end
- **Marking:** T4

■ Maximum Ratings ($T_A=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Repetitive peak reverse voltage	V_{RRM}	V		75
Peak forward surge current	I_{FSM}	A	$t_p=10\mu\text{s}$	2
Average forward current	I_{FAV}	mA		200
Power dissipation	P_{tot}	mW		350
Thermal Resistance	R_{thJA}	$^\circ\text{C}/\text{W}$		315
Maximum junction temperature	T_j	$^\circ\text{C}$		-55 ~ +150
Storage temperature range	T_{stg}	$^\circ\text{C}$		-55 ~ +150

■ Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless otherwise specified)

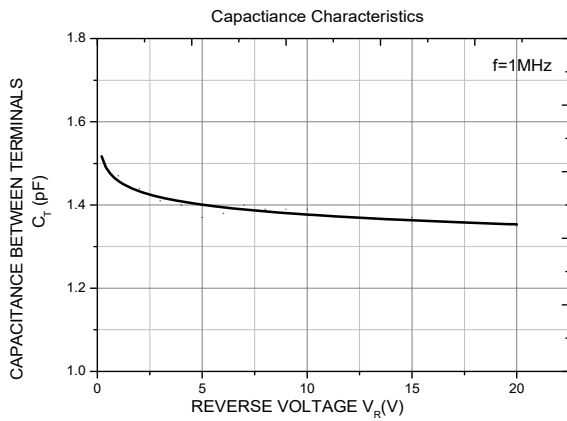
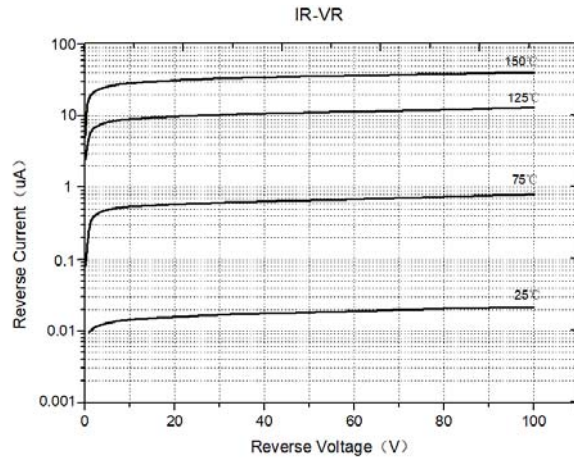
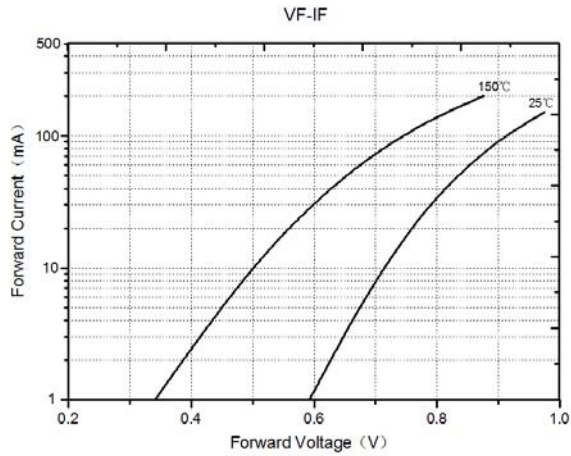
PARAMETER	SYMBOL	UNIT	Conditions	Min	Typ	Max
Maximum Forward voltage	V_F	V	$I_F=1\text{mA}$			0.715
	V_F	V	$I_F=10\text{mA}$			0.855
	V_F	V	$I_F=50\text{mA}$			1.0
	V_F	V	$I_F=150\text{mA}$			1.25
Maximum Reverse current	I_R	μA	$V_R=75\text{V}$			1.0
Minimum Breakdown voltage	V_R	V	$I_R=100\mu\text{A}$	100		
Maximum Diode capacitance	C_D	pF	$V_R=V_F=0\text{V}$, $f=1\text{MHz}$			4
Maximum Reverse recovery time	t_{rr}	ns	$I_F=10\text{mA}$, $I_{rr}=0.1I_R$, $R_L=100\Omega$			6

BAS16WS

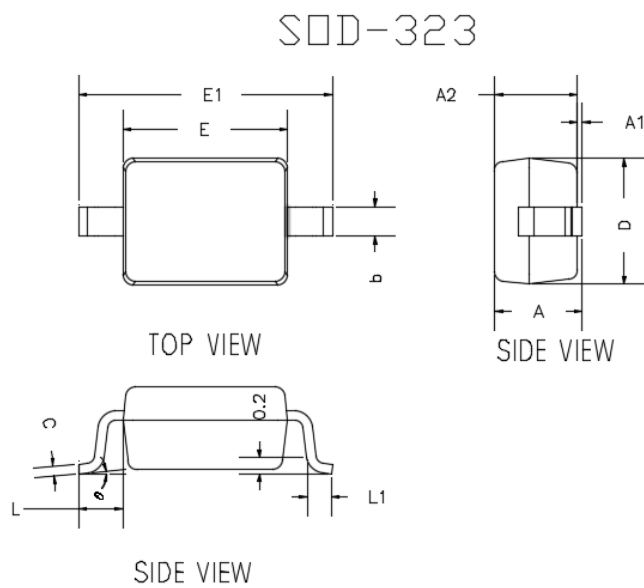
■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BAS16WS	F2	Approximate 0.0048	3000	30000	120000	7" reel

■ Characteristics (Typical)

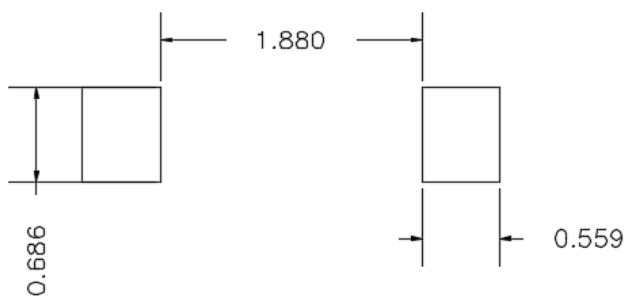


■Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
θ	0°	8°	0°	8°

■Soldering Footprint



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT

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